

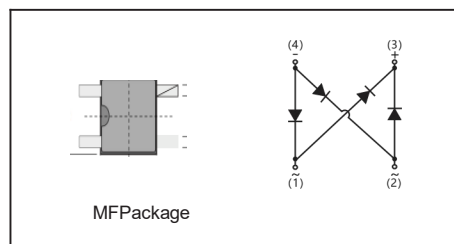
**0.8A SURFACE MOUNT GLASS PASSIVATED BRIDGE RECTIFIER**

**FEATURES:**

- Glass Passivated Chip Junction
- Reverse Voltage - 100 to 1000 V
- Forward Current - 0.8 A
- High Surge Current Capability
- Designed for Surface Mount Application

**PINNING**

PIN	DESCRIPTION
1	Input Pin (~)
2	Input Pin (~)
3	Output Anode (+)
4	Output Cathode (-)



**MECHANICAL DATA**

- Case: MBF
- Terminals: Solderable per MIL-STD-750, Method 2026
- Approx. Weight: 75mg/0.0026oz

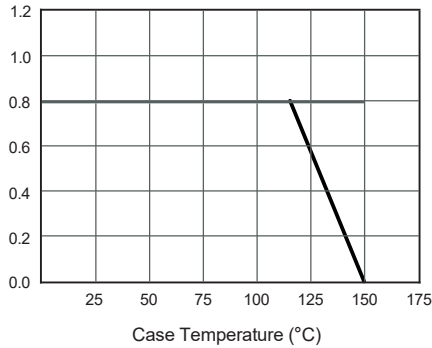
**Maximum Ratings and Electrical characteristics**

Ratings at 25 °C ambient temperature unless otherwise specified.  
Single phase half-wave 60 Hz, resistive or inductive load, for capacitive load current derate by 20 %.

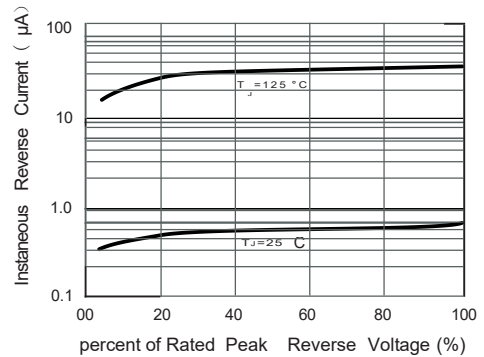
Parameter	Symbols	MB1F	MB2F	MB4F	MB6F	MB8F	MB10F	Units
Maximum Repetitive Peak Reverse Voltage	$V_{RRM}$	100	200	400	600	800	1000	V
Maximum RMS voltage	$V_{RMS}$	70	140	280	420	560	700	V
Maximum DC Blocking Voltage	$V_{DC}$	100	200	400	600	800	1000	V
Maximum Average Forward Rectified Current @ Fig.1	$I_{F(AV)}$	0.8						A
Peak Forward Surge Current,8.3ms Single Half Sine-wave Superimposed on Rated Load (JEDEC method)	$I_{FSM}$	30						A
Peak Forward Surge Current,1.0ms Single Half Sine-wave Superimposed on Rated Load (JEDEC method)	$I_{FSM}$	60						A
$I^2t$ Rating for fusing (3ms≤t≤8.3ms)	$I^2t$	3.7						A <sup>2</sup> S
Max Instantaneous Forward Voltage at 0.8 A	$V_F$	1.1						V
Maximum DC Reverse Current at Rated DC Reverse Voltage $T_a = 25^{\circ}C$ $T_a = 125^{\circ}C$	$I_R$	5 40						$\mu A$
Typical Junction Capacitance <sup>(1)</sup>	$C_j$	7						pF
Typical Thermal Resistance <sup>(2)</sup>	$R_{\theta JA}$ $R_{\theta JC}$ $R_{\theta JL}$	45 15 25						$^{\circ}C/W$
Operating and Storage Temperature Range	$T_j, T_{stg}$	-55 ~ +150						$^{\circ}C$

(1) Measured at 1 MHz and applied reverse voltage of 4 V D.C  
(2) Mounted on glass epoxy PC board with 4×1.5"×1.5" (3.81×3.81 cm) copper pad.

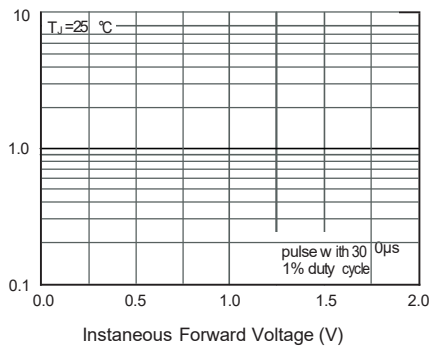
**Fig.1 Average Rectified Output Current Derating Curve**



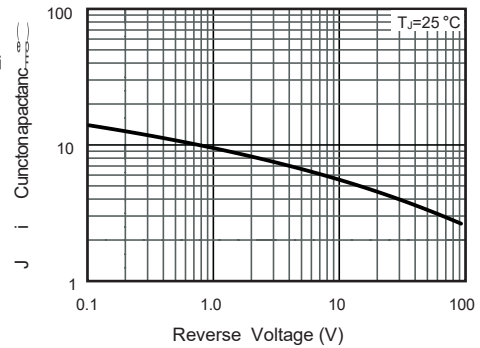
**Fig.2 Typical Reverse Characteristics**



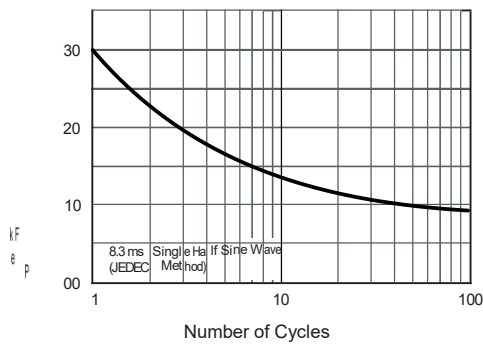
**Fig.3 Typical Instantaneous Forward Characteristics**



**Fig.4 Typical Junction Capacitance**

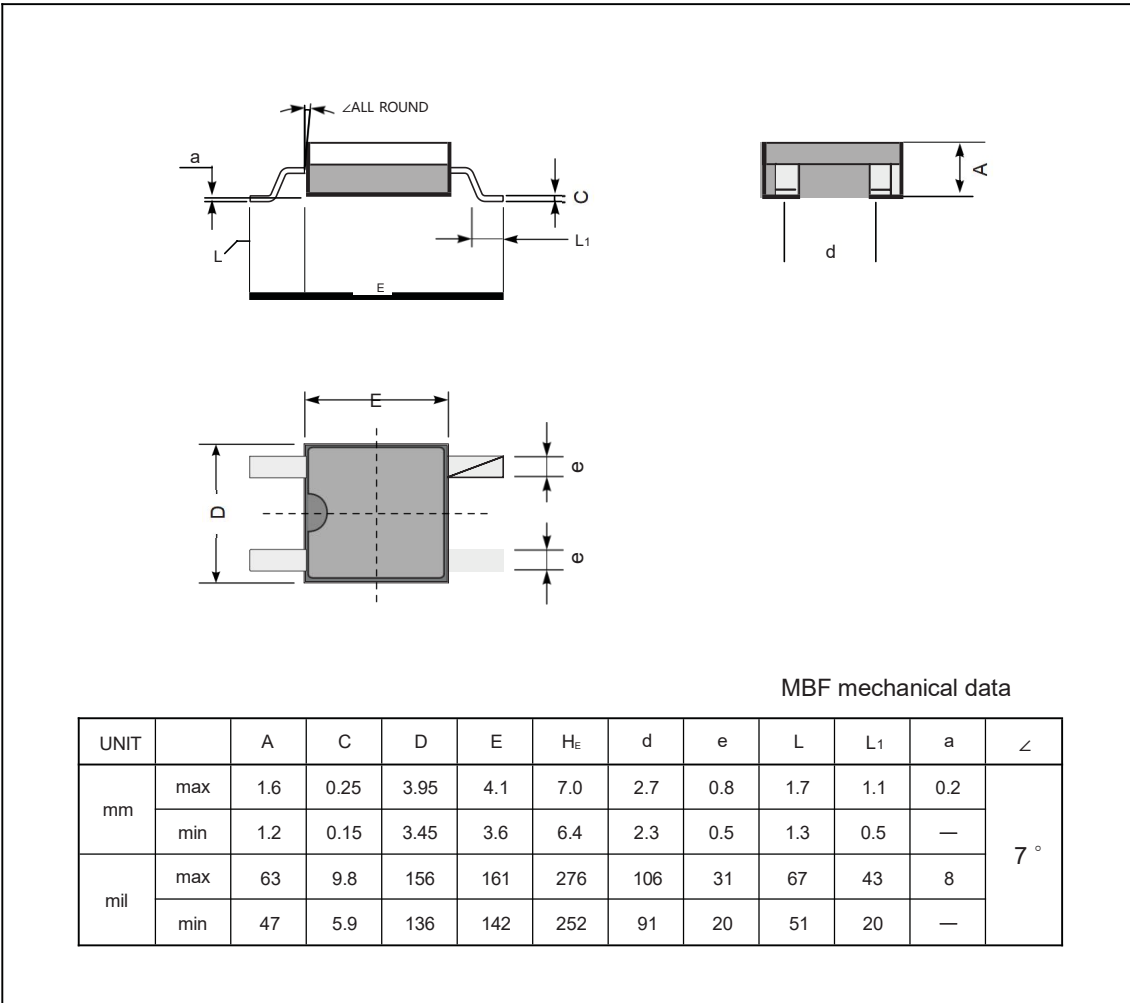


**Fig.5 Maximum Non-Repetitive Peak Forward Surge Current**

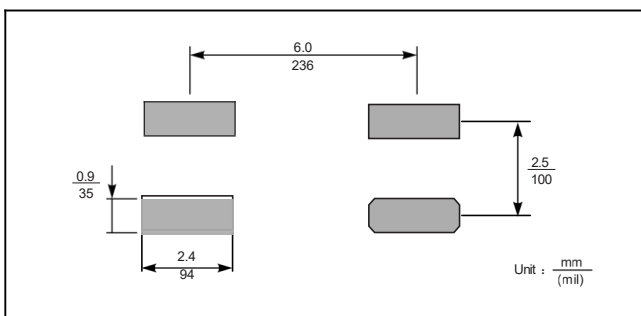


## PACKAGE OUTLINE

Plastic surface mounted package; 4 leads



### The recommended mounting pad size



### Marking

Type number	Marking code
MB1F	MB1F
MB2F	MB2F
MB4F	MB4F
MB6F	MB6F
MB8F	MB8F
MB10F	MB10F